

## 3.3V CMOS 12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH WITH 3-STATE OUTPUTS AND BUS-HOLD

#### FEATURES:

- 0.5 MICRON CMOS Technology
- Typical tsk(0) (Output Skew) < 250ps</li>
- ESD > 2000V per MIL-STD-883, Method 3015;
  > 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP, and 0.40mm pitch TVSOP packages
- Extended commercial range of 40°C to + 85°C
- Vcc = 3.3V ± 0.3V, Normal Range
- Vcc = 2.7V to 3.6V, Extended Range
- Vcc = 2.5V ± 0.2V
- CMOS power levels (0.4µW typ. static)
- Rail-to-Rail output swing for increased noise margin

#### Drive Features for ALVCHR16260:

- Balanced Output Drivers: ±12mA
- Low switching noise

## **APPLICATIONS:**

• 3.3V High Speed Systems

3.3V and lower voltage computing systems

### **DESCRIPTION:**

This 12-bit to 24-bit multiplexed D-type latch is built using advanced dual metal technology. The ALVCHR16260 is used in

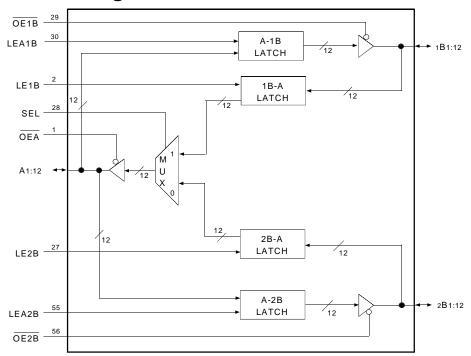
### **Functional Block Diagram**

applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing address and data information in microprocessor or bus-interface applications. This device also is useful in memory interleaving applications.

Three 12-bit I/O ports (A1-A12, 1B1-1B12, and 2B1-2B12) are available for address and/or data transfer. The output-enable (OE1B, OE2B, and OEA) inputs control the bus transceiver functions. The OE1B and OE2B control signals also allow bank control in the A-to-B direction. Address and/or data information can be stored using the internal storage latches. The latch-enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch-enable input is high, the latch is transparent. When the latch-enable input goes low, the data present at the inputs is latched and remains latched until the latch-enable input is returned high.

The ALVCHR16260 has series resistors in the device output structure which will significantly reduce line noise when used with light loads. This driver has been designed to drive  $\pm 12$ mA at the designated threshold levels.

The ALVCHR16260 has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

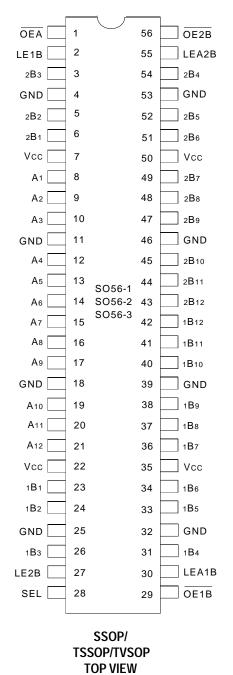


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#### EXTENDED COMMERCIAL TEMPERATURE RANGE

#### JULY 1999

#### **PIN CONFIGURATION**



## ABSOLUTE MAXIMUM RATING (1)

Symbol	Description	Max.	Unit
VTERM <sup>(2)</sup>	Terminal Voltage	– 0.5 to + 4.6	V
	with Respect to GND		
VTERM <sup>(3)</sup>	Terminal Voltage	– 0.5 to	V
	with Respect to GND	Vcc + 0.5	
Tstg	Storage Temperature	– 65 to + 150	°C
Ιουτ	DC Output Current	– 50 to + 50	mA
Ік	Continuous Clamp Current,	± 50	mA
	VI < 0  or  VI > VCC		
Іок	Continuous Clamp Current, Vo < 0	- 50	mA
Icc	Continuous Current through	±100	mA
lss	each Vcc or GND		
	•	•	NEW16link

#### NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. VCC terminals.

3. All terminals except Vcc.

### **CAPACITANCE** (TA = +25°C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Тур.	Max.	Unit
Cin	Input Capacitance	VIN = 0V	5	7	pF
Соит	Output Capacitance	Vout = 0V	7	9	pF
Ci/o	I/O Port Capacitance	Vin = 0V	7	9	pF

NOTE:

1. As applicable to the device type.

#### **PIN DESCRIPTION**

Pin Names	I/O	Description
Ax(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's Address/Data bus. <sup>(1)</sup>
1 <b>Bx</b> (1:12)	I/O	Bidirectional Data Port 1B. Connected to the even path or even bank of memory. <sup>(1)</sup>
2 <b>Bx(1</b> :12)	I/O	Bidirectional Data Port 2B. Connected to the odd path or odd bank of memory. <sup>(1)</sup>
LEA1B	-	Latch Enable Input for A-1B latch. The latch is open when LEA1B is HIGH. Data from the A port is latched on the HIGH to LOW transition of LEA1B.
LEA2B	Ι	Latch Enable Input for A-2B latch. The latch is open when LEA2B is HIGH. Data from the A port is latched on the HIGH to LOW transition of LEA2B.
LE1B	Ι	Latch Enable Input for 1B-A latch. The latch is open when LE1B is HIGH. Data from the 1B port is latched on the HIGH to LOW transition of LE1B.
LE2B	Ι	Latch Enable Input for 2B-A latch. The latch is open when LE2B is HIGH. Data from the 2B port is latched on the HIGH to LOW transition of LE2B.
SEL	Ι	1B or 2B Path Selection. When HIGH, SEL enables data transfer from 1B port to A port. When LOW, SEL enables data transfer from 2B port to A port.
OEA	Ι	Output Enable for A port (Active LOW)
OE1B	Ι	Output Enable for 1B port (Active LOW)
OE2B	I	Output Enable for 2B port (Active LOW)

#### NOTE:

1. These pins have "Bus-Hold." All other pins are standard inputs, outputs, or I/Os.

## **FUNCTION TABLES (1)**

# **B TO A** ( $\overline{OEB}$ = H)

		Outputs				
1 <b>Bx</b>	2Bx	SEL	LE1B	LE2B	<b>OEA</b>	Ах
Н	Х	Н	Н	Х	L	Н
L	Х	Н	Н	Х	L	L
Х	Х	Н	L	Х	L	A <sub>0</sub> <sup>(2)</sup>
Х	Н	L	Х	Н	L	Н
Х	L	L	Х	Н	L	L
Х	Х	L	Х	L	L	A <sub>0</sub> <sup>(2)</sup>
Х	Х	Х	Х	Х	Н	Z

#### NOTES:

1. H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

Z = High-Impedance

2. Output level before the indicated steady-state input conditions were established.

# A TO B ( $\overline{OEB} = H$ )

	Inputs					puts
Ax	LEA1B	LEA2B	OE1B	OE2B	1Bx	2Bx
Н	Н	Н	L	L	Н	Н
L	Н	Н	L	L	L	L
Н	Н	L	L	L	Н	2B <sub>0</sub> <sup>(2)</sup>
L	Н	L	L	L	L	2B <sub>0</sub> <sup>(2)</sup>
Н	L	Н	L	L	1B <sub>0</sub> <sup>(2)</sup>	Н
L	L	Н	L	L	1B <sub>0</sub> <sup>(2)</sup>	L
Х	L	L	L	L	1B <sub>0</sub> <sup>(2)</sup>	2B <sub>0</sub> <sup>(2)</sup>
Х	Х	Х	Н	Н	Z	Z
Х	Х	Х	L	Н	Active	Z
Х	Х	Х	Н	L	Z	Active
Х	Х	Х	L	L	Active	Active

# **DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE**

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = – 40°C to +85°C

Symbol	Parameter	Test C	onditions	Min.	Typ. <sup>(1)</sup>	Max.	Unit
Vih	Input HIGH Voltage Level	Vcc = 2.3V to 2.7V		1.7	_	_	V
		Vcc = 2.7V to 3.6V		2	_		
VIL	Input LOW Voltage Level	Vcc = 2.3V to 2.7V		_	_	0.7	V
		Vcc = 2.7V to 3.6V		_	_	0.8	
Ін	Input HIGH Current	Vcc = 3.6V	VI = VCC	_	_	± 5	μA
lil	Input LOW Current	Vcc = 3.6V	VI = GND	-	_	± 5	
Іоzн	High Impedance Output Current	Vcc = 3.6V	Vo = Vcc	_	_	± 10	μA
Iozl	(3-State Output pins)		Vo = GND	_	_	± 10	μA
Vik	Clamp Diode Voltage	VCC = 2.3V, IIN = - 18mA		_	- 0.7	- 1.2	V
Vн	Input Hysteresis	Vcc = 3.3V		_	100		mV
ICCL		Vcc = 3.6V		_	0.1	40	μA
Іссн	Quiescent Power Supply Current	VIN = GND or Vcc					
Iccz							
$\Delta$ lcc	Quiescent Power Supply	One input at Vcc – 0.6V,		_	—	750	μA
	Current Variation	other inputs at Vcc or GND					NEW16lin

NOTE:

1. Typical values are at Vcc = 3.3V, +25°C ambient.

### **BUS-HOLD CHARACTERISTICS**

Symbol	Parameter <sup>(1)</sup>		Test Conditions		Typ. <sup>(2)</sup>	Max.	Unit
Івнн	Bus-Hold Input Sustain Current	Vcc = 3.0V	VI = 2.0V	- 75	—	_	μA
IBHL			VI = 0.8V	75	—	_	
Івнн	Bus-Hold Input Sustain Current	Vcc = 2.3V	VI = 1.7V	- 45	—	_	μA
IBHL			VI = 0.7V	45	—	_	
Івнно	Bus-Hold Input Overdrive Current	Vcc = 3.6V	VI = 0 to 3.6V	—	—	± 500	μA
IBHLO							

NOTES:

1. Pins with Bus-hold are identified in the pin description.

2. Typical values are at Vcc = 3.3V, +25°C ambient.

### **OUTPUT DRIVE CHARACTERISTICS**

Symbol	Parameter	Test	Conditions <sup>(1)</sup>	Min.	Max.	Uni
/он	Output HIGH Voltage	Vcc = 2.3V to 3.6V	IOH = -0.1mA	Vcc - 0.2	_	V
		Vcc = 2.3V	Iон = – 4mA	1.9	_	
			IOH = - 6mA	1.7	_	
		Vcc = 2.7V	Iон = – 4mA	2.2	_	
			Iон = - 8mA	2	_	
		Vcc = 3.0V	Iон = – 6mA	2.4	_	
			Iон = – 12mA	2	_	
/ol	Output LOW Voltage	Vcc = 2.3V to 3.6V	Iol = 0.1mA	-	0.2	V
		Vcc = 2.3V	IOL = 4mA	-	0.4	
			IOL = 6mA	-	0.55	
		Vcc = 2.7V	IOL = 4mA	_	0.4	
			IOL = 8mA	-	0.6	
		Vcc = 3.0V	IOL = 6mA	—	0.55	
		IOL = 12mA	_	0.8		

NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate Vcc range. TA = − 40°C to + 85°C.

# OPERATING CHARACTERISTICS, T<sub>A</sub> = $25^{\circ}$ C

			Vcc = 2.5V ± 0.2V	Vcc = 3.3V ± 0.3V	Unit
Symbol	Parameter	Test Conditions	Typical	Typical	
Cpd	Power Dissipation Capacitance	CL = 0pF, f = 10Mhz	37	41	۶D
	Outputs enabled				рг
CPD	Power Dissipation Capacitance		4	7	"Г
	Outputs disabled				pF

# SWITCHING CHARACTERISTICS<sup>(1)</sup>

		Vcc = 2.	5V ± 0.2V	Vcc	= 2.7V	$Vcc = 3.3V \pm 0.3V$			
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Uni	
<b>t</b> PLH	Propagation Delay	1	5.9	_	5.8	1.2	4.9	ns	
<b>t</b> PHL	Ax to 1Bx or Ax to 2Bx								
<b>t</b> PLH	Propagation Delay	1	5.9	-	5.8	1.2	4.9	ns	
<b>t</b> PHL	1Bx to Ax or 2Bx to Ax								
<b>t</b> PLH	Propagation Delay	1	6.1	-	5.9	1	5	ns	
<b>t</b> PHL	LExB to Ax								
<b>t</b> PLH	Propagation Delay	1	6.1	-	5.9	1	5	ns	
<b>t</b> PHL	LEA1B to 1Bx or LEA2B to 2Bx								
<b>t</b> PLH	Propagation Delay	1	7.4	-	7.1	1.1	6.1	ns	
<b>t</b> PHL	SEL to Ax								
tрzн	Output Enable Time	1	7.2	-	7.1	1	6	ns	
tpzl	OEA to Ax, OE1B to 1Bx, or OE2B to 2Bx								
tphz	Output Disable Time	1	6.2	-	5.5	1.3	5.1	ns	
tplz	OEA to Ax, OE1B to 1Bx, or OE2B to 2Bx								
tsu	Setup Time, data before LE1B, LE2B, LEA1B, LEA2B	1.4	_	1.1	_	1.1	_	ns	
tн	Hold Time, data after LE1B, LE2B, LEA1B, LEA2B	1.6	-	1.9	-	1.5	_	ns	
tw	Pulse Width, LE1B, LE2B, LEA1B, or LEA2B HIGH	3.3	_	3.3	_	3.3	_	ns	
tsκ(o)	Output Skew <sup>(2)</sup>	_	_	_	_	_	500	ps	

1. See test circuits and waveforms. TA =  $-40^{\circ}$ C to  $+85^{\circ}$ C.

2. Skew between any two outputs of the same package and switching in the same direction.

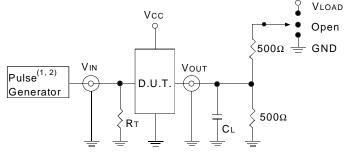
#### IDT74ALVCHR16260 3.3V CMOS 12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH

# **TEST CIRCUITS AND WAVEFORMS**

#### **TEST CONDITIONS**

Symbol	Vcc <sup>(1)</sup> = 3.3V±0.3V	Vcc <sup>(1)</sup> = 2.7V	Vcc <sup>(2)</sup> = 2.5V±0.2V	Unit
Vload	6	6	2 x Vcc	٧
Vih	2.7	2.7	Vcc	V
VT	1.5	1.5	Vcc/2	٧
Vlz	300	300	150	mV
Vhz	300	300	150	mV
CL	50	50	30	pF NEW16link

### **TEST CIRCUITS FOR ALL OUTPUTS**



#### **DEFINITIONS:**

ALVC Link CL= Load capacitance: includes jig and probe capacitance.

- RT = Termination resistance: should be equal to ZOUT of the Pulse
- Generator.

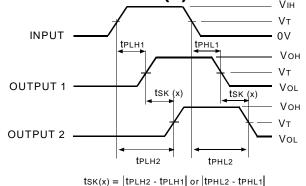
#### NOTES:

- 1. Pulse Generator for All Pulses: Rate  $\leq$  10MHz; tF  $\leq$  2.5ns; tR  $\leq$  2.5ns.
- 2. Pulse Generator for All Pulses: Rate  $\leq$  10MHz; tF  $\leq$  2ns; tR  $\leq$  2ns.

#### SWITCH POSITION

Test	Switch
Open Drain	VLOAD
Disable Low	
Enable Low	
Disable High	GND
Enable High	
All Other tests	Open
	NEW16link

### **OUTPUT SKEW** - TSK (x)



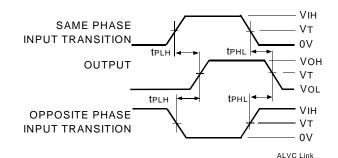
ALVC Link

#### NOTES:

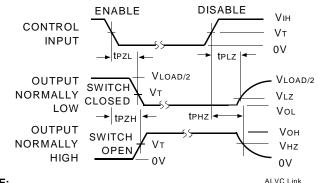
1. For tsk(o) OUTPUT1 and OUTPUT2 are any two outputs.

2. For tsk(b) OUTPUT1 and OUTPUT2 are in the same bank.

#### **PROPAGATION DELAY**



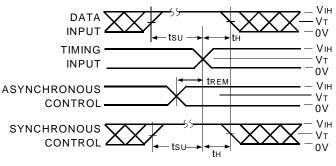
# **ENABLE AND DISABLE TIMES**



#### NOTE:

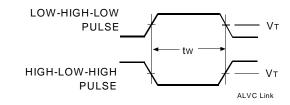
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

#### SET-UP, HOLD, AND RELEASE TIMES

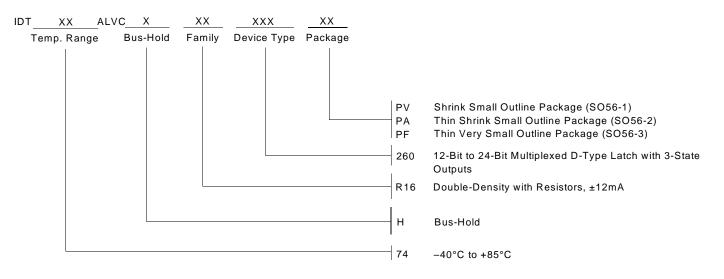


ALVC Link

### **PULSEWIDTH**



#### **ORDERING INFORMATION**





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